

Title (en)
AN IMPROVED LASER ABLATEABLE MATERIAL

Title (de)
EIN VERBESSERTER LASERABSCHIEDBARES MATERIAL

Title (fr)
MATERIAU AMELIORE POUVANT SUBIR UNE ABLATION PAR UN RAYONNEMENT LASER

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Application
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Abstract (en)
[origin: WO9627212A1] This invention discloses a method for coating an integrated circuit (3) with a layer of plasma deposited polymers (PDP) ablateable by visible light laser radiation.

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